

Title (en)

METHOD OF MAKING SILVER/ME0 CONTACT PLATES WITH A WELDABLE OR SOLDERABLE BACKING

Publication

**EP 0299099 B1 19910116 (DE)**

Application

**EP 87110116 A 19870714**

Priority

EP 87110116 A 19870714

Abstract (en)

[origin: EP0299099A1] Because of their high MeO component, such small contact plates cannot be directly soldered or welded onto contact carriers. For this purpose, such a small contact plate must be provided with a layer which can be soldered or welded. According to the invention, it is proposed that such a layer be applied in the course of hot-press plating (hot-press welding), in an inert gas or reducing atmosphere. <IMAGE>

IPC 1-7

**H01H 1/02; H01H 11/04**

IPC 8 full level

**H01H 11/04** (2006.01)

CPC (source: EP)

**H01H 11/045** (2013.01)

Cited by

DE102008056263A1; US8992826B2; EP1387370A1; CN1047462C; US5598629A; US5799771A; WO2010051922A3; WO9311550A1; WO9508833A1; EP2946395A1

Designated contracting state (EPC)

AT BE CH DE FR GB LI NL SE

DOCDB simple family (publication)

**EP 0299099 A1 19890118; EP 0299099 B1 19910116;** AT E60163 T1 19910215; DE 3767487 D1 19910221

DOCDB simple family (application)

**EP 87110116 A 19870714;** AT 87110116 T 19870714; DE 3767487 T 19870714